

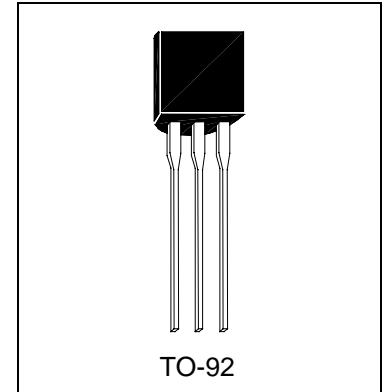


HSB1109S

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HSB1109S is designed for low frequency and high voltage amplifier applications complementary pair with HSD1609S.



Absolute Maximum Ratings

- Maximum Temperatures
 - Storage Temperature -50 ~ +150 °C
 - Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 - Total Power Dissipation (Ta=25°C) 900 mW
- Maximum Voltages and Currents (Ta=25°C)
 - VCBO Collector to Base Voltage -160 V
 - VCEO Collector to Emitter Voltage -160 V
 - VEBO Emitter to Base Voltage -5 V
 - IC Collector Current -100 mA

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-160	-	-	V	IC=-10uA, IE=0
BVCEO	-160	-	-	V	IC=-1mA, IB=0
VEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-10	uA	VCB=-140V, IE=0
*VCE(sat)	-	-	-2	V	IC=-30mA, IB=-3mA
VBE(on)	-	-	-1.5	V	VCE=-5V, IC=-10mA
*hFE1	60	-	320		VCE=-5V, IC=-10mA
*hFE2	30	-	-		VCE=-5V, IC=-1mA
fT	-	140	-	MHz	VCE=-5V, IC=-10mA, f=100MHz
Cob	-	5.5	-	pF	VCB=-10V, IE=0, f=1MHz

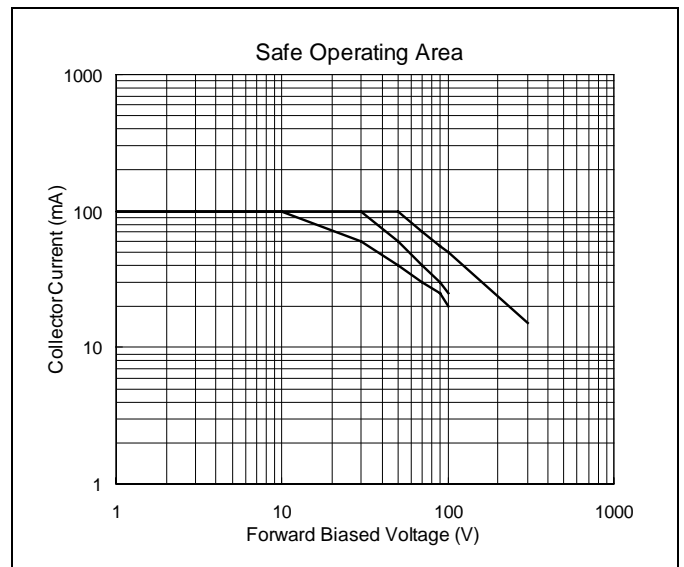
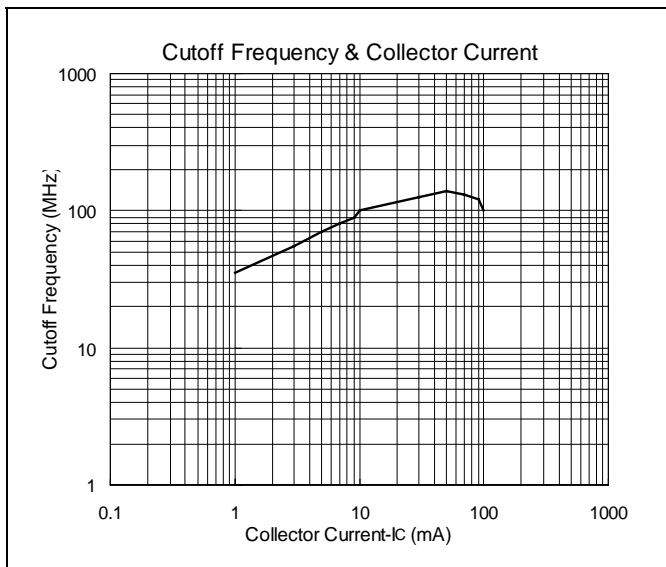
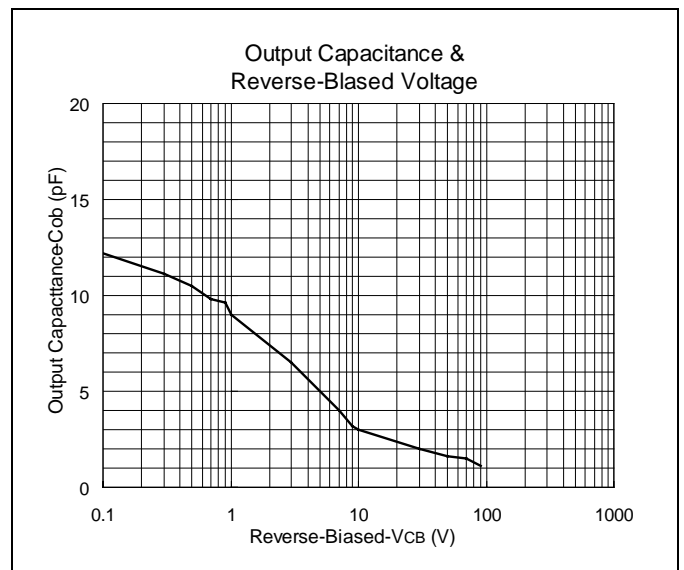
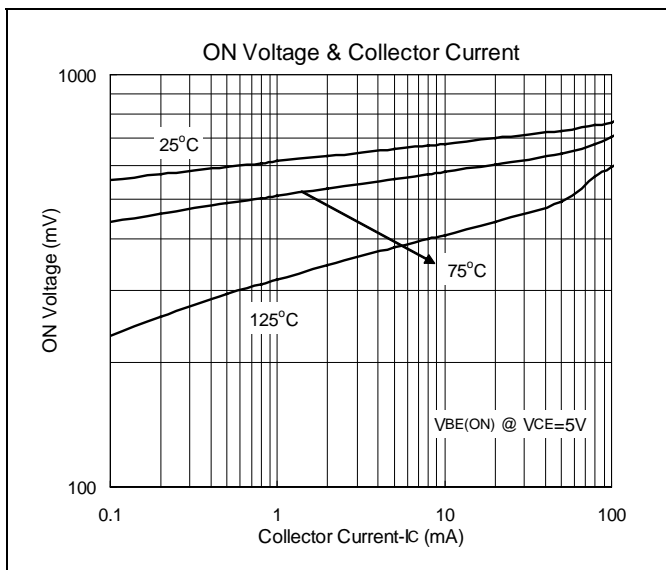
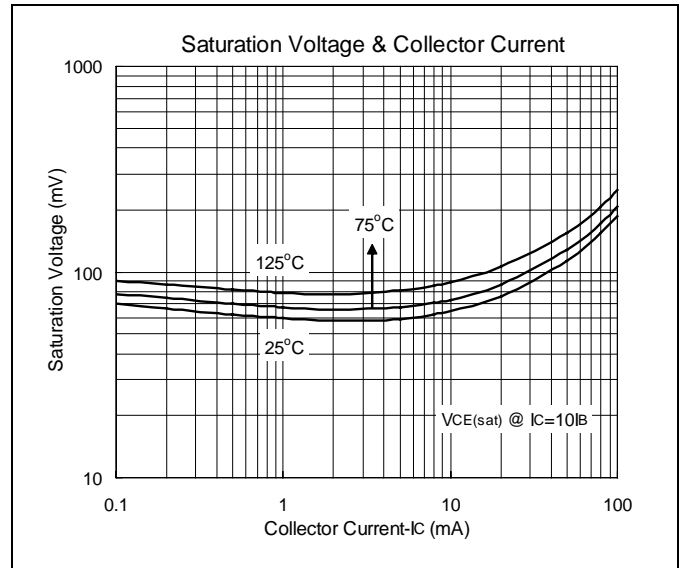
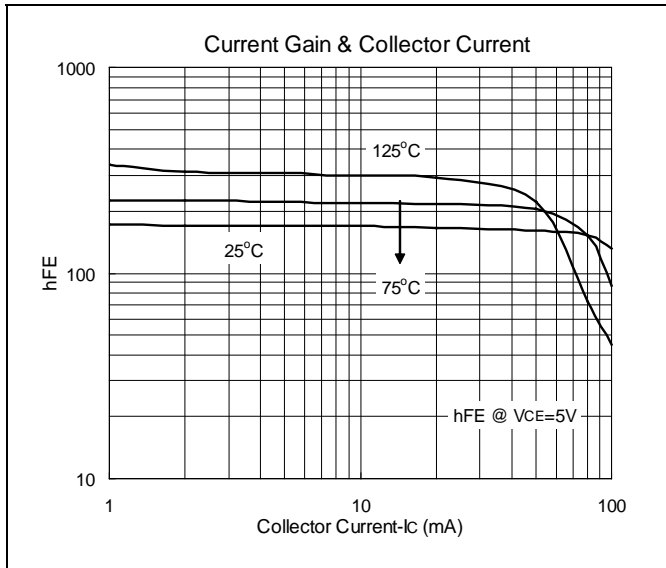
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

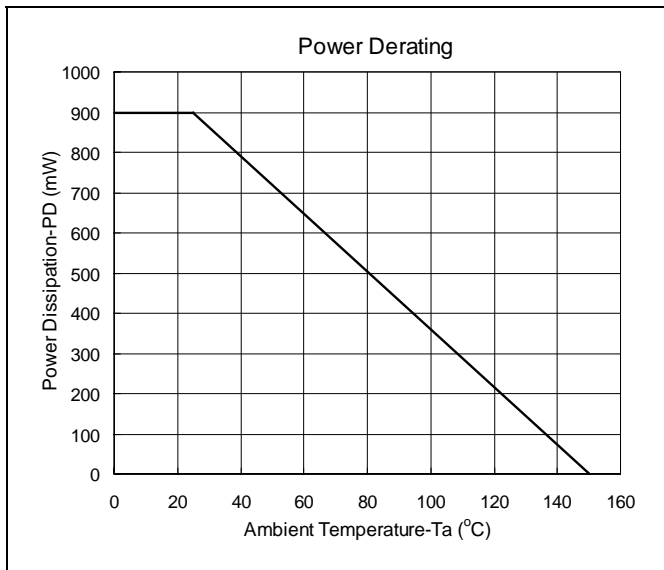
Classification Of hFE1

Rank	B	C	D
Range	60-120	100-200	160-320



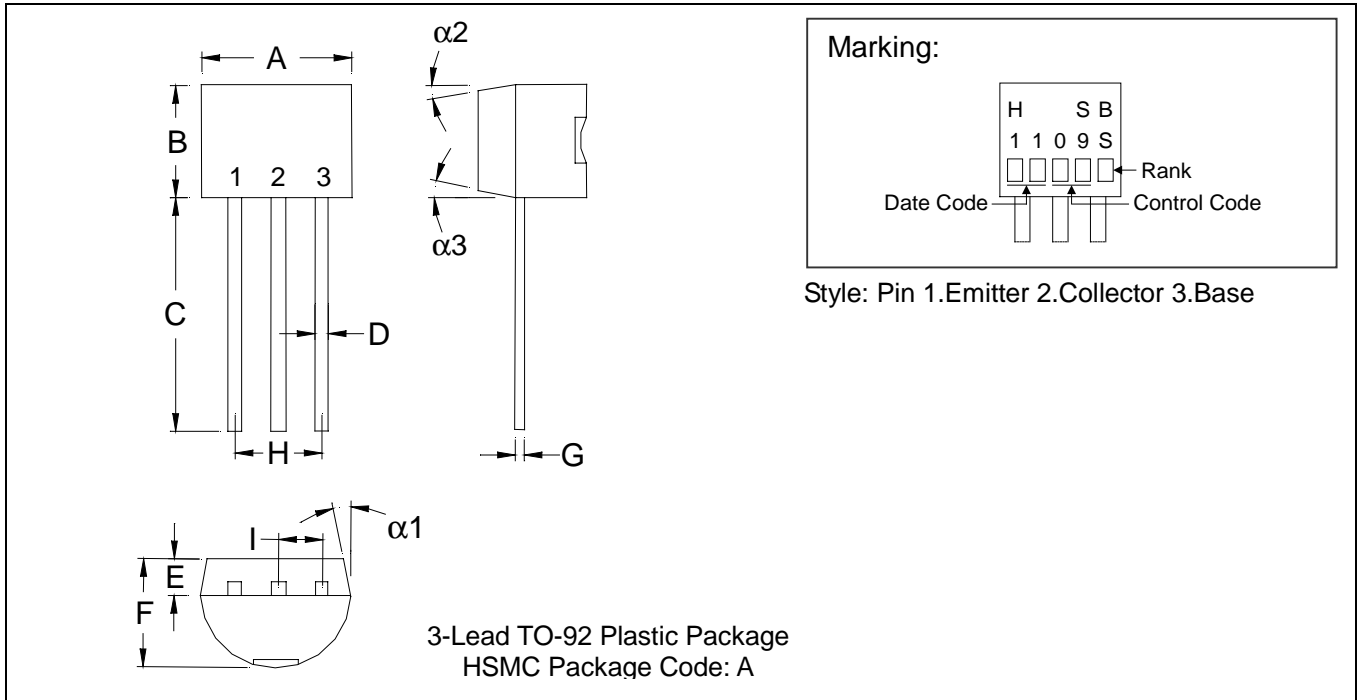
Characteristics Curve







TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

- Notes:**
1. Dimension and tolerance based on our Spec. dated Apr. 25, 1996.
 2. Controlling dimension: millimeters.
 3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4. If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F., No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel: 886-3-5983621~5 Fax: 886-3-5982931